

AN 1996:153958 HCAPLUS  
 DN 124:239719  
 TI Composite **solders** and their manufacture for high-temperature  
 uses  
 IN Kishimoto, Koichi; Kubokawa, Atsushi  
 PA Tanaka Electronics Ind, Japan  
 SO Jpn. Kokai Tokkyo Koho, 6 pp.  
 CODEN: JKXXAF  
 DT Patent  
 LA Japanese  
 FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
	-----	---	-----	-----	-----
PI	JP 08001372	A2	19960109	JP 1994-129054	19940610
PRAI	JP 1994-129054		19940610		

AB The **solders** consist of **solder** materials contg.  
 powders, and the **solder** materials comprise **Sn** alloys  
 contg. 5-15% **Sb** and 2-15% **Ag**. The process comprises  
 cold-working the **solder** materials. The **solders** have  
 high ductility at 170.degree. and cold-workability and are esp. suitable  
 for bonding parts in semiconductor devices used at high temp.